

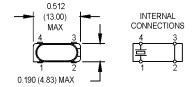


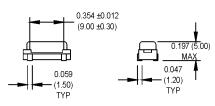




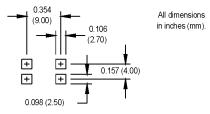


Package A

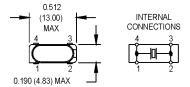


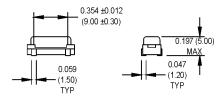


SUGGESTED SOLDER PAD LAYOUT

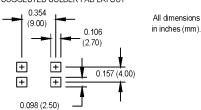


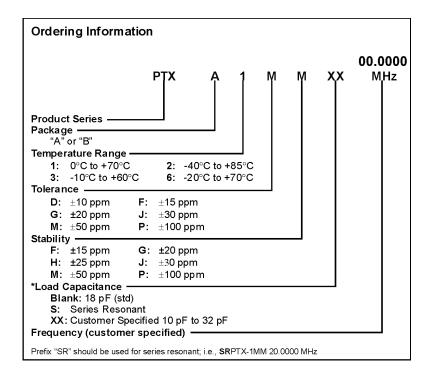
Package B





SUGGESTED SOLDER PAD LAYOUT





PARAMETERS	VALUE
Frequency Range*	3.579 to 72.000 MHz
Tolerance @ +25° C	See Table Above
Stability	See Table Above
Aging	±5 ppm/yr. Max.
Standard Operating Conditions	See Table Above
Storage Temperature	-55°C to +105°C
Shunt Capacitance	7 pF Max.
Load Capacitance	18 pF Std.
Equivalent Series Resistance (ESR), Max.	
Fundamental (AT cut)	
3.579 to 3.999 MHz	180 Ω
4.000 to 4.999 MHz	150 Ω
5.000 to 6.999 MHz	100 Ω
7.000 to 14.999 MHz	50 Ω
15.000 to 23.999 MHz	40 Ω
24.000 to 40.000 MHz	30 Ω
Third Overtones (AT cut)	
40.000 to 72.000 MHz	80 Ω
Drive Level	100 μW Max.
Holder	HC-49/US-SMD
Mechanical Shock	MIL-STD-202, Method 213, C
Vibration	MIL-STD-202, Method 201 & 204
Solder Conditions ¹	230°C for 10 seconds max.
Thermal Cycle	MIL-STD-883, Method 1010, B

^{*} Because this product is based on AT-Strip technology, not all frequencies in the range stated are available. Contact the factory for availability of specific frequencies.

See figure #1

MtronPTI reserves the right to make changes to the product(s) and service(s) described herein without notice. No liability is assumed as a result of their use or application.